

REMARKS

This Election and Preliminary Amendment is submitted in response to an Office Action mailed May 21, 2002. In the Office Action, the Examiner restricted the claims in the application and required the Applicants to elect between Group I, comprising claims 1-8, and Group II, comprising claims 9-12. Applicants have elected Group II without traverse. In addition, Applicants have added new claims 13-28, all of which are directed to the same subject matter as Group II. Claims 9-28 remain pending in the application. Applicants respectfully request reconsideration of the application and allowance of all pending claims in view of the above election and amendments.

Charge Deposit Account

Please charge our Deposit Account No. 02-2666 for any additional fee(s) that may be due in this matter, and please credit the same deposit account for any overpayment.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Date: 7-30-02

Todd M. Becker  
Todd M. Becker  
Attorney for Applicant(s)  
Registration No. 43,487

Blakely, Sokoloff, Taylor & Zafman LLP  
12400 Wilshire Boulevard, Seventh Floor  
Los Angeles CA 90025-1030  
Phone: 206-292-8600  
Facsimile: 206-292-8606

Enclosures: Postcard  
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**APPENDIX A – CLAIMS**  
**MARKED-UP REPLACEMENT CLAIMS**

Pursuant to 37 C.F.R. § 1.121(c), the amended claims shown below in marked-up form correspond to the amended clean claims found in the amendment.

9. (Amended) A semiconductor [A HSQFN (High Stand-off Quad Flat Non-leaded)] package, comprising:

a leadframe having a die pad and bonding pads, wherein said die pad is designed to carry a die adhered [adhesived] thereon by adhesive material, wherein said die pad and bonding pads are separated;

a plurality of bonding wires connected between said bonding pads and said die for electrical communication; and

molding compound encompassing said die, said bonding wires and a first surface of said leadframe, leaving the terminal of said bonding pads and the lower surface of said die pad exposed out of said molding compound for providing excellent thermal dissipation from said package, wherein said exposed bonding pads is used for communication terminal for said package.

10. (Amended) The semiconductor [HSQFN] package of claim 9, wherein said die is attached by adhesive material.
11. (Amended) The semiconductor [HSQFN] package of claim 10, wherein said adhesive material includes epoxy.
12. (Amended) The semiconductor [HSQFN] package of claim 9, wherein said bonding wires includes gold.